

Title (en)

METHOD FOR PRODUCING A SYSTEM SUPPORT AND ELECTRONIC COMPONENTS

Title (de)

HERSTELLUNGSVERFAHREN FÜR EINEN SYSTEMTRÄGER UND FÜR ELEKTRONISCHE BAUTEILE

Title (fr)

PROCEDE DE PRODUCTION D'UN SUPPORT DE SYSTEME ET DE COMPOSANTS ELECTRONIQUES

Publication

EP 1295336 A2 20030326 (DE)

Application

EP 01949240 A 20010607

Priority

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Abstract (en)

[origin: WO0201634A2] The invention relates to a system support (5) for semiconductor chips (1) and electronic components (2) which are produced on said system support (5). The system support (5) has a base substrate (11) on which outer contact elements (6) are located. These outer contact elements have a cross-section (7) in the form of a rivet with a rivet head area (8), a rivet shaft area (9) and a rivet foot area (10). This ensures that the outer contact elements (6) are securely anchored in the housing, which consists of a plastic mass (4).

IPC 1-7

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IPC 8 full level

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